

### Advanced Information

- 4 194 304 words by 36-Bit organization (alternative 8 388 608 words by 18-bit)
- Fast access and cycle time
  - 60 ns access time
  - 110 ns cycle time (-60 version)
  - 70 ns access time
  - 130 ns cycle time (-70 version)
- Fast page mode capability
  - 40 ns cycle time (-60 version)
  - 45 ns cycle time (-70 version)
- Single + 5 V ( $\pm 10\%$ ) supply
- Low power dissipation
  - max. 7260 mW active (-60 version)
  - max. 6600 mW active (-70 version)
  - CMOS – 66 mW standby
  - TTL – 132 mW standby
- CAS-before-RAS refresh
  - RAS-only-refresh
  - Hidden-refresh
- 12 decoupling capacitors mounted on substrate
- All inputs, outputs and clocks fully TTL compatible
- 72 pin Single in-Line Memory Module (L-SIM-72-12) with 22.9 mm (900 mil) height
- Utilizes eight 4M x 4-DRAMs and four 4M x 1-DRAMs in SOJ packages
- 2048 refresh cycles / 32 ms
- Optimized for use in byte-write parity applications
- Tin-Lead contact pads (S-version)
- Gold contact pads (GS-version)

The HYM 364020S/GS-60/-70 is a 16 MByte DRAM module organized as 4 194 304 words by 36-Bit in a 72-pin single-in-line package comprising eight HYB 5117400BJ 4M × 4 DRAMs and four HYB 514100BJ 4M × 1 DRAMs in 300 mil wide SOJ-packages mounted together with twelve 0.2 µF ceramic decoupling capacitors on a PC board.

The HYM 364020S/GS-60/-70 can also be used as a 8 388 608 words by 18-bits dynamic RAM module by means of connecting DQ0 and DQ18, DQ1 and DQ19, DQ2 and DQ20, ..., DQ17 and DQ35, respectively.

Each HYB 5117400BJ and HYB 514100BJ is described in the data sheet and is fully electrical tested and processed according to SIEMENS standard quality procedure prior to module assembly. After assembly onto the board, a further set of electrical tests is performed.

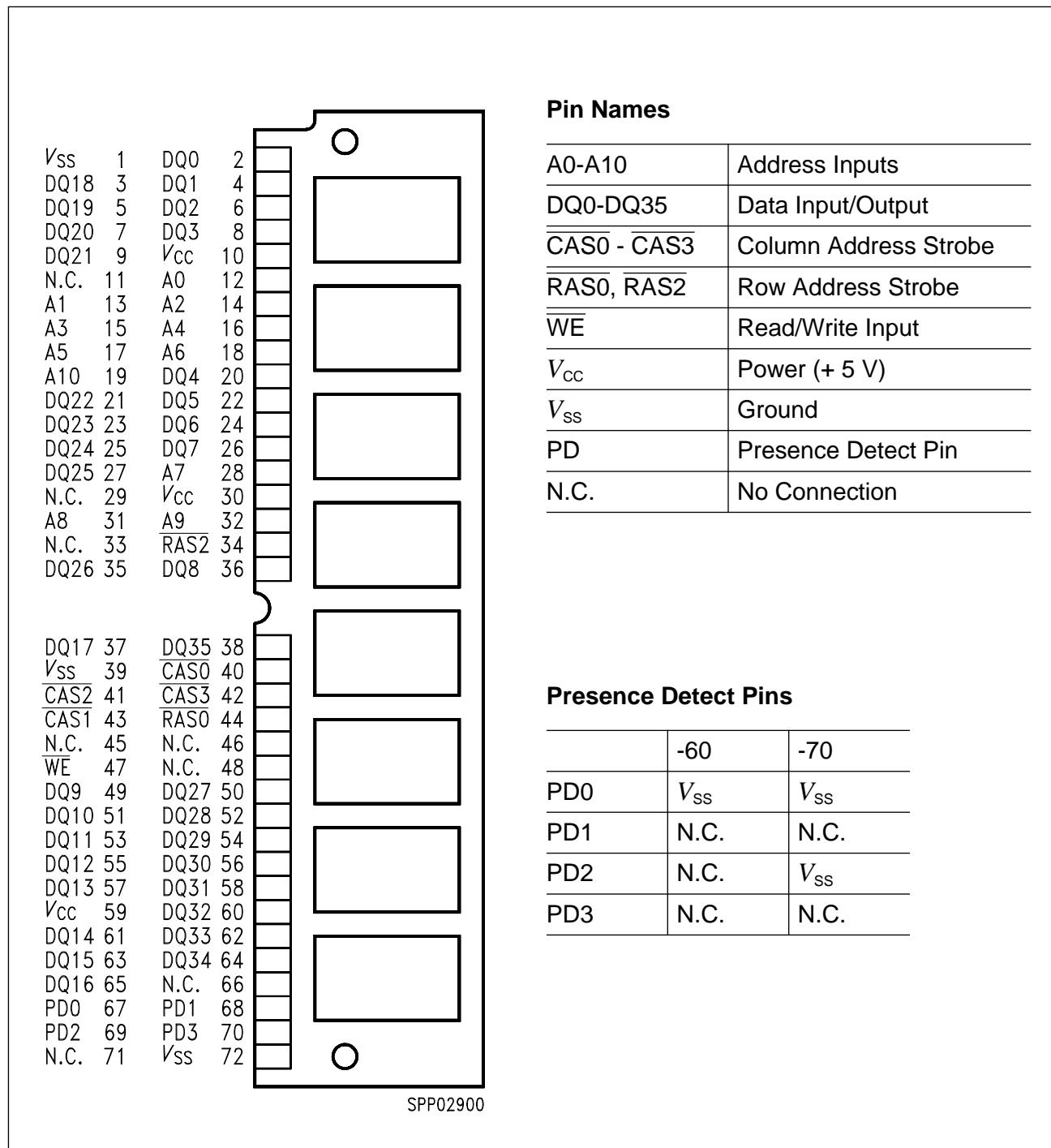
The speed of the module can be detected by the use of four presence detect pins.

The common I/O feature on the HYM 364020S/GS-60/-70 dictates the use of early write cycles.

### **Ordering Information**

Type	Ordering Code	Package	Description
HYM 364020S-60	Q67100-Q2006	L-SIM-72-12	DRAM Module (access time 60 ns)
HYM 364020S-70	On request	L-SIM-72-12	DRAM Module (access time 70 ns)
HYM 364020GS-60	Q67100-Q982	L-SIM-72-12	DRAM Module (access time 60 ns)
HYM 364020GS-70	Q67100-Q983	L-SIM-72-12	DRAM Module (access time 70 ns)

## Pin Configuration (top view)

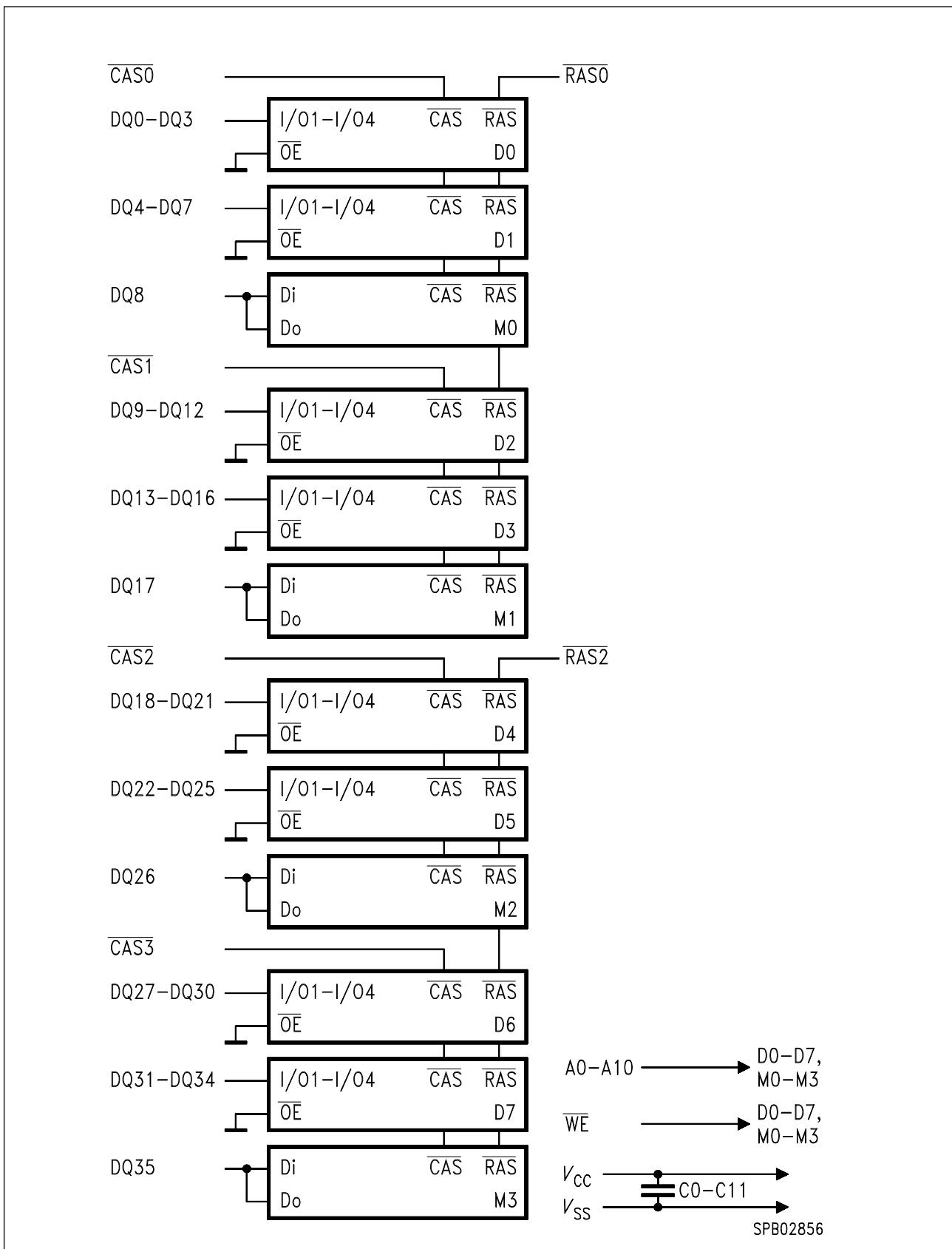


## Pin Names

A0-A10	Address Inputs	
DQ0-DQ35	Data Input/Output	
CAS0 - CAS3	Column Address Strobe	
RAS0, RAS2	Row Address Strobe	
WE	Read/Write Input	
V <sub>cc</sub>	Power (+ 5 V)	
V <sub>ss</sub>	Ground	
PD	Presence Detect Pin	
N.C.	No Connection	

## Presence Detect Pins

	-60	-70
PD0	V <sub>ss</sub>	V <sub>ss</sub>
PD1	N.C.	N.C.
PD2	N.C.	V <sub>ss</sub>
PD3	N.C.	N.C.

**Block Diagram**

**Absolute Maximum Ratings**

Operation temperature range .....	0 to + 70 °C
Storage temperature range.....	- 55 to 125 °C
Input/output voltage .....	- 0.5 V to min ( $V_{CC} + 0.5$ , 7.0) V
Power supply voltage.....	- 1 to + 7 V
Power dissipation.....	9.3 W
Data out current (short circuit) .....	50 mA

**Note:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage of the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**DC Characteristics**

$T_A = 0$  to 70 °C,  $V_{CC} = 5$  V ± 10 %

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Input high voltage	$V_{IH}$	2.4	$V_{CC} + 0.5$	V	1)
Input low voltage	$V_{IL}$	- 0.5	0.8	V	1)
Output high voltage ( $I_{OUT} = - 5$ mA)	$V_{OH}$	2.4	-	V	1)
Output low voltage ( $I_{OUT} = 4.2$ mA)	$V_{OL}$	-	0.4	V	1)
Input leakage current (0 V < $V_{IN}$ < 6.5 V, all other pins = 0 V)	$I_{I(L)}$	- 20	20	µA	1)
Output leakage current (DO is disabled, 0 V < $V_{OUT}$ < 5.5 V)	$I_{O(L)}$	- 10	10	µA	1)
Average $V_{CC}$ supply current (RAS, CAS, address cycling, $t_{RC} = t_{RC}$ min) -60 version -70 version	$I_{CC1}$	-	1320 1200	mA mA	2),3),4)
Standby $V_{CC}$ supply current (RAS = CAS = $V_{IH}$ )	$I_{CC2}$	-	24	mA	
Average $V_{CC}$ supply current during RAS only refresh cycles (RAS cycling, CAS = $V_{IH}$ , $t_{RC} = t_{RC}$ min) -60 version -70 version	$I_{CC3}$	-	1320 1200	mA mA	2),4)

**DC Characteristics<sup>1)</sup> (cont'd)**

<b>Parameter</b>	<b>Symbol</b>	<b>Limit Values</b>		<b>Unit</b>	<b>Test Condition</b>
		<b>min.</b>	<b>max.</b>		
Average $V_{CC}$ supply current during fast page mode ( $\overline{RAS} = V_{IL}$ , $\overline{CAS}$ , address cycling, $t_{PC} = t_{PC\ min}$ )	$I_{CC4}$	—	920 840	mA mA	2),3),4)
-60 version -70 version		—			
Standby $V_{CC}$ supply current ( $\overline{RAS} = \overline{CAS} = V_{CC} - 0.2\text{ V}$ )	$I_{CC5}$	—	12	mA	
Average $V_{CC}$ supply current during CAS-before-RAS refresh mode ( $\overline{RAS}$ , $\overline{CAS}$ cycling, $t_{RC} = t_{RC\ min}$ )	$I_{CC6}$	—	1320 1200	mA mA	2),4)
-60 version -70 version		—			

**Capacitance** $T_A = 0$  to  $70^\circ\text{C}$ ,  $V_{CC} = 5\text{ V} \pm 10\%$ ,  $f = 1\text{ MHz}$ 

<b>Parameter</b>	<b>Symbol</b>	<b>Limit Values</b>		<b>Unit</b>
		<b>min.</b>	<b>max.</b>	
Input capacitance (A0 to A10, WE)	$C_{I1}$	—	75	pF
Input capacitance ( $\overline{RAS0}$ , $\overline{RAS2}$ )	$C_{I2}$	—	45	pF
Input capacitance ( $\overline{CAS0}$ - $\overline{CAS3}$ )	$C_{I3}$	—	25	pF
I/O capacitance (DQ0-DQ7,DQ9-DQ16,DQ18-DQ25,DQ27-DQ34)	$C_{IO1}$	—	15	pF
I/O capacitance (DQ8,DQ17,DQ26,DQ35)	$C_{IO2}$	—	25	pF

**AC Characteristics** 5)6) $T_A = 0$  to  $70$  °C,  $V_{CC} = 5$  V ± 10 %,  $t_T = 5$  ns

Parameter	Symbol	Limit Values				Unit	Note		
		-50		-60					
		min.	max.	min.	max.				

**Common Parameters**

Random read or write cycle time	$t_{RC}$	90	—	110	—	ns	
RAS precharge time	$t_{RP}$	30	—	40	—	ns	
RAS pulse width	$t_{RAS}$	50	10k	60	10k	ns	
CAS pulse width	$t_{CAS}$	13	10k	15	10k	ns	
Row address setup time	$t_{ASR}$	0	—	0	—	ns	
Row address hold time	$t_{RAH}$	8	—	10	—	ns	
Column address setup time	$t_{ASC}$	0	—	0	—	ns	
Column address hold time	$t_{CAH}$	10	—	15	—	ns	
RAS to CAS delay time	$t_{RCD}$	18	37	20	45		
RAS to column address delay time	$t_{RAD}$	13	25	15	30	ns	
RAS hold time	$t_{RSH}$	13		15	—	ns	
CAS hold time	$t_{CSH}$	50		60	—	ns	
CAS to RAS precharge time	$t_{CRP}$	5	—	5	—	ns	
Transition time (rise and fall)	$t_T$	3	50	3	50	ns	7
Refresh period	$t_{REF}$	—	32	—	32	ms	

**Read Cycle**

Access time from RAS	$t_{RAC}$	—	50	—	60	ns	8, 9
Access time from CAS	$t_{CAC}$	—	13	—	15	ns	8, 9
Access time from column address	$t_{AA}$	—	25	—	30	ns	8, 10
Column address to RAS lead time	$t_{RAL}$	25	—	30	—	ns	
Read command setup time	$t_{RCS}$	0	—	0	—	ns	
Read command hold time	$t_{RCH}$	0	—	0	—	ns	11
Read command hold time referenced to RAS	$t_{RRH}$	0	—	0	—	ns	11
CAS to output in low-Z	$t_{CLZ}$	0	—	0	—	ns	8
Output buffer turn-off delay	$t_{OFF}$	0	13	0	15	ns	12

**AC Characteristics (cont'd) <sup>5)6)</sup>** $T_A = 0 \text{ to } 70 \text{ }^\circ\text{C}$ ,  $V_{CC} = 5 \text{ V} \pm 10 \text{ \%}$ ,  $t_T = 5 \text{ ns}$ 

Parameter	Symbol	Limit Values				Unit	Note		
		-50		-60					
		min.	max.	min.	max.				

***Early Write Cycle***

Write command hold time	$t_{WCH}$	8	—	10	—	ns	
Write command pulse width	$t_{WP}$	8	—	10	—	ns	
Write command setup time	$t_{WCS}$	0	—	0	—	ns	13
Write command to <u>RAS</u> lead time	$t_{RWL}$	13	—	15	—	ns	
Write command to <u>CAS</u> lead time	$t_{CWL}$	13	—	15	—	ns	
Data setup time	$t_{DS}$	0	—	0	—	ns	14
Data hold time	$t_{DH}$	10	—	10	—	ns	14

***Fast Page Mode Cycle***

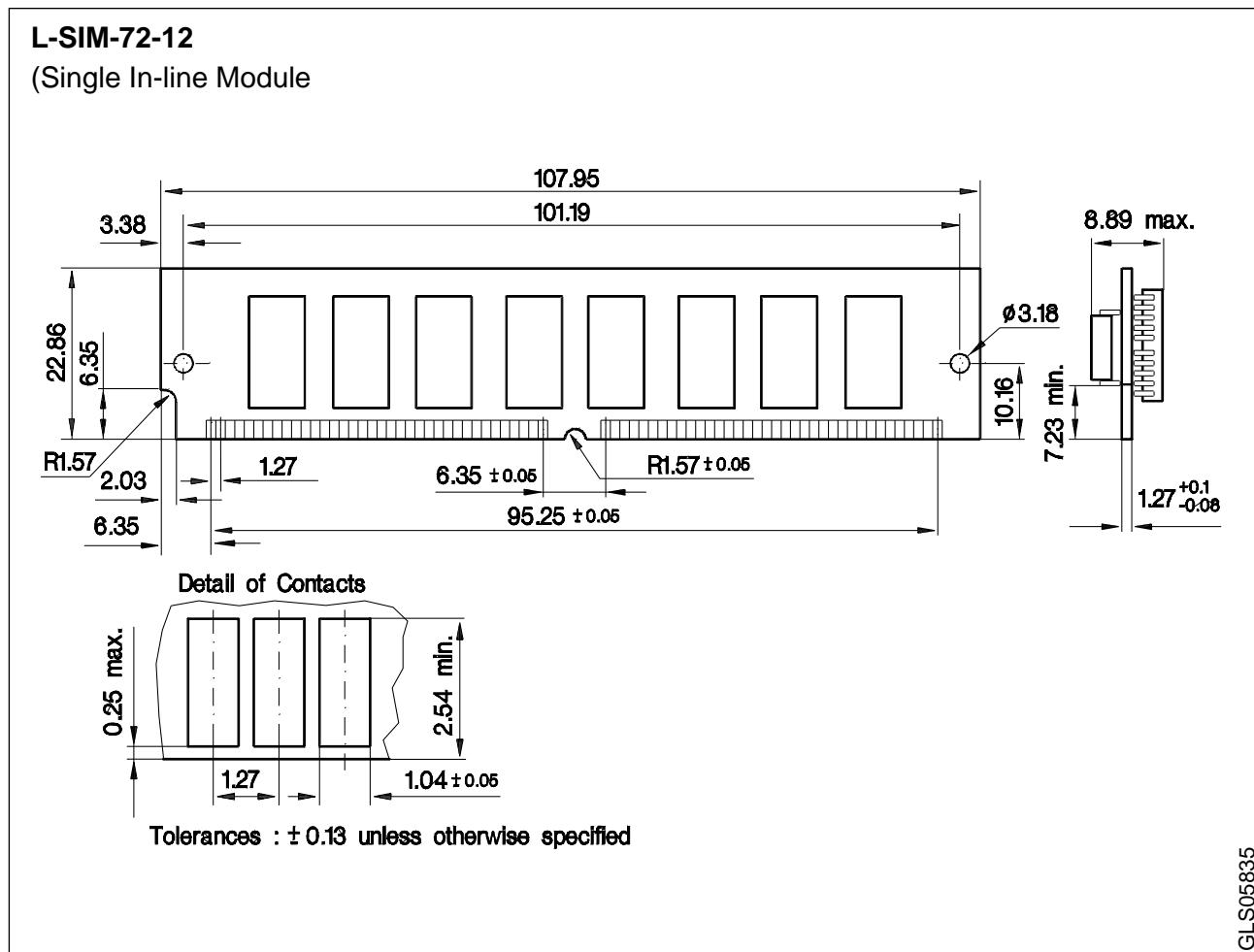
Fast page mode cycle time	$t_{PC}$	35	—	40	—	ns	
CAS precharge time	$t_{CP}$	10	—	10	—	ns	
Access time from <u>CAS</u> precharge	$t_{CPA}$	—	30	—	35	ns	7
RAS pulse width	$t_{RAS}$	50	200k	60	200k	ns	
CAS precharge to <u>RAS</u> Delay	$t_{RHCP}$	30	—	35	—	ns	

**CAS-before-RAS Refresh Cycle**

CAS setup time	$t_{CSR}$	10	—	10	—	ns	
CAS hold time	$t_{CHR}$	10	—	10	—	ns	
RAS to <u>CAS</u> precharge time	$t_{RPC}$	5	—	5	—	ns	
Write to <u>RAS</u> precharge time	$t_{WRP}$	10	—	10	—	ns	
Write hold time referenced to <u>RAS</u>	$t_{WRH}$	10	—	10	—	ns	

**Notes:**

- 1) All voltages are referenced to  $V_{SS}$ .
- 2)  $I_{CC1}, I_{CC3}, I_{CC4}$  and  $I_{CC6}$  depend on cycle rate.
- 3)  $I_{CC1}$  and  $I_{CC4}$  depend on output loading. Specified values are measured with the output open.
- 4) Address can be changed once or less while  $\overline{RAS} = V_{IL}$ . In the case of  $I_{CC4}$  it can be changed once or less during a fast page mode cycle ( $t_{PC}$ ).
- 5) An initial pause of 200  $\mu s$  is required after power-up followed by 8 RAS cycles of which at least one cycle has to be a refresh cycle, before proper device operation is achieved. In case of using internal refresh counter, a minimum of 8 CAS-before-RAS initialization cycles instead of 8 RAS cycles are required.
- 6) AC measurements assume  $t_T = 5$  ns.
- 7)  $V_{IH\ (min.)}$  and  $V_{IL\ (max.)}$  are reference levels for measuring timing of input signals. Transition times are also measured between  $V_{IH}$  and  $V_{IL}$ .
- 8) Measured with a load equivalent to 2 TTL loads and 100 pF.
- 9) Operation within the  $t_{RCD\ (max.)}$  limit ensures that  $t_{RAC\ (max.)}$  can be met.  $t_{RCD\ (max.)}$  is specified as a reference point only: If  $t_{RCD}$  is greater than the specified  $t_{RCD\ (max.)}$  limit, then access time is controlled by  $t_{CAC}$ .
- 10) Operation within the  $t_{RAD\ (max.)}$  limit ensures that  $t_{RAC\ (max.)}$  can be met.  $t_{RAD\ (max.)}$  is specified as a reference point only: If  $t_{RAD}$  is greater than the specified  $t_{RAD\ (max.)}$  limit, then access time is controlled by  $t_{AA}$ .
- 11) Either  $t_{RCH}$  or  $t_{RRH}$  must be satisfied for a read cycle.
- 12)  $t_{OFF\ (max.)}$  define the time at which the outputs achieve the open-circuit condition and are not referenced to output voltage levels.
- 13)  $t_{WCS}$  is not a restrictive operating parameter. This is included in the data sheet as electrical characteristics only. If  $t_{WCS} > t_{WCS\ (min.)}$ , the cycle is an early write cycle and the I/O pin will remain open-circuit (high impedance) through the entire cycle.
- 14) These parameters are referenced to the  $\overline{CAS}$  leading edge.

**Package Outline****Sorts of Packing**

Package outlines for tubes, trays etc. are contained in our Data Book "Package Information".

SMD = Surface Mounted Device

Dimensions in mm